

onsemi				10/27/2021
Base Part		NCP705	HF	Pb-free
Orderable Part		NCP705EMT33TCG	Total weight (mg) 9	
Homogenous Material	Weight (mg)	Substance in Mat.	CAS #	% Avg. Weight
Die	0.7	Silicon (Si)	7440-21-3	100
Die Attach	0.19	Epoxy resin	proprietary data	2.5
		Silver (Ag)	7440-22-4	84.5
		Phenolic Resin	proprietary data	2.5
		Inorganic filler	proprietary data	2.5
		Dicyandiamine	461-58-5	0.5
		Formaldehyde Polymer	9003-36-5	7.5
Lead Frame	3.1	Silver (Ag)	7440-22-4	1
		Tin (Sn)	7440-31-5	0.25
		Zinc (Zn)	7440-66-6	0.22
		Chromium (Cr)	7440-47-3	0.25
		Copper (Cu)	7440-50-8	98.28
Mold Compound-Black	4.65	Epoxy and Phenolic Resin	40216-08-8	8
		Carbon Black (C)	1333-86-4	0.5
		Aluminum Hydroxide (Al(OH)3)	21645-51-2	2
		Fused Silica (SiO2)	60676-86-0	86.5
		Phenolic Resin (Novolac)	9003-35-4	3
Plating	0.18	Tin (Sn)	7440-31-5	100
Wire Bond - Au	0.18	Gold (Au)	7440-57-5	100
<p>Materials Disclosure Disclaimer: Even though all possible efforts have been made to provide you with the most accurate information, we cannot guarantee to its accuracy since the data has been compiled based on the ranges provided, and some information provided by the subcontractors and raw material suppliers may have been withheld to protect their business proprietary information. Thus this information is provided only as estimates, and do not include trace levels of dopants and metal materials contained within silicon devices in the finished products. There is no intentional use of RoHS restricted substances. Lead (Pb) and lead oxide (PbO) are exempted with the RoHS exemption 7(a), 7(c) and 15. For further explanation on material composition calculations, please view our Product Chemical Content Brochure at:</p> <p>https://www.onsemi.com/pub/Collateral/BRD8022-D.PDF</p>				